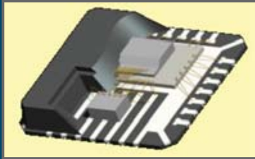
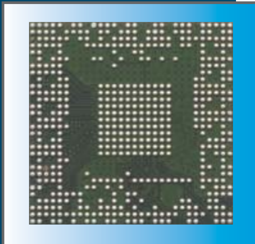
Advanced Packaging Update:

Market and Technology Trends

Vol. 3-0414





The third volume of the Advanced Packaging Update provides an analysis of the outsourced assembly and test (OSAT) industry with revenue trends and planned CAPEX for 2014. A special section focuses on trends in mobile device packaging. An analysis of high-end and low-end mobile phones from India is provided. Trends in fan-out wafer level packages (FO-WLPs) are detailed. New packages such as the Molded Interconnect Solution (MIS) technology are discussed. The report examines trends in automotive electronics with a look into future packaging needs. An economic outlook based on key economic indicators is provided.

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